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 YOUR MODULE NO.:
 OUR MODULE NO.:
 K350QVG-V2-F

 YOUR SPEC NO.:
 OUR FULL SPEC NO.:
 FS-K350QVG-V2-F-04

Remark:

**K350QVG-V2-F** is fully compatible with **K350QVG-V1-F** and can be used to replace the K350QVG-V1-F (K350QVG-V1-F already phased out as the EOL of tft cell.), no need to changing software and hardware. (Already approved by TI on Stellaris M3 Evaluation board.)

APPROVED BY					

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## K350QVG-V2-F

### **Product**

Standard LCD Module 320 x RGB x 240 Dots 3.5" 262K colors TFT display Wide temperature With white LED backlight With Touch Panel

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#### **1. Document revision history :**

1. Document revision history :							
DOCUMENT REVISION	DATE	DESCRIPTION	PREPARED BY	APPROVED BY			
01	2008.04.28	First Release.	MF Zou				
02	2010.06.30	Revised typing error	MF Zou				
03	2010.07.15	Update packing reference	MF Zou				
04	2012.05.28	Revised typing error	MF Zou				



#### 2. General Description

- 3.5"(diagonal), 320 x RGB x 240 dots, 262K colors, Transmissive, TFT LCD module.
- Viewing Direction: 12 o'clock.
- Driving IC: SSD2119 or equivalent TFT controller/driver.
- 18-bit/16-bit/8-bit data bus (parallel RGB interface/8080 parallel system interface). 4-wire/3-wire SPI interface.
- With Touch Panel.
- With internal voltage booster.
- Logic voltage: 3.3V (typ.).

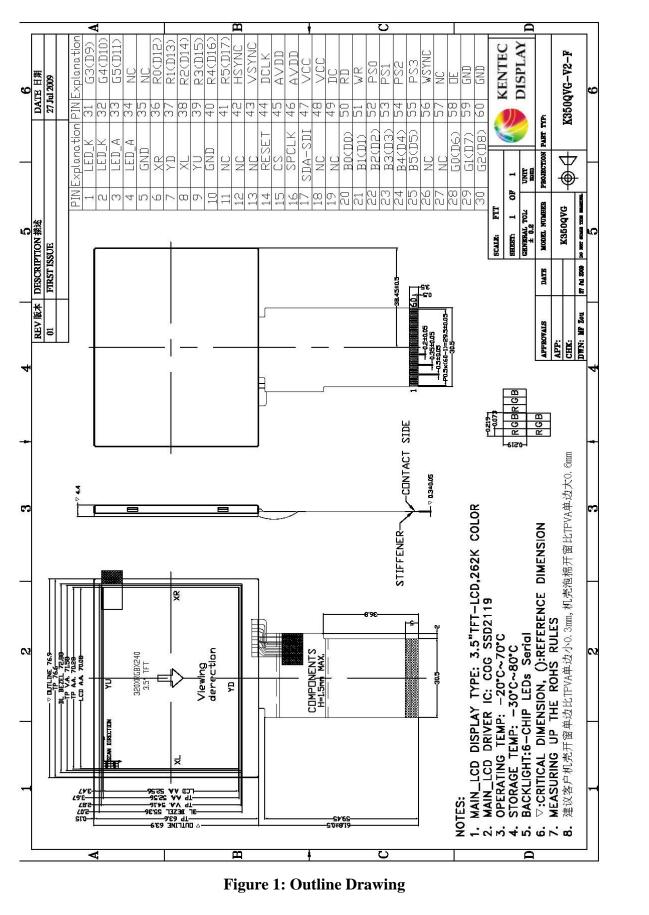
#### **3.** Mechanical Specifications

The mechanical detail is shown in Fig. 1 and summarized in Table 1 below.

		Table 1	
Par	rameter	Specifications	Unit
Outline dimensions		76.9(W) x 63.9(H) x 4.4(D) (Exclude FPC, cables of backlight)	mm
	View area	72.88(W) x 55.36(H)	mm
	TP view area	71.58 (W) x 54.2(H)	mm
Color TFT	LCD active area	70.08(W) x 52.56(H)	mm
320xRGBx240	Display format	320 x RGB x 240	dots
	Color configuration	RGB stripes	-
	Dot size	0.219(RGB)(W) x 0.219(H)	mm
V	Veight	~40	grams



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#### 4. Interface signals

4. 1110	0	Table 2: Pin assignment						
Pin No.	Symbol	Description						
1-2	LED_K							
3-4	LED_A	- Power supply for LED backlight						
5	GND	Power supply (system ground)						
6	XR							
7	YD	– Terminal of touch panel.						
8	XL							
9	YU							
10	GND	Power supply (system ground)						
11-13	NC	No connection						
14	RESET	System reset pin						
15	CS	Chip select pin						
16	SPCLK	Clock pin of serial interface						
17	SDA-SDI	Data pin of serial interface						
18-19	NC	No connection						
20-25	B[0-5]	Blue data 6-bit/18bit bi-directional (D0-D5)						
26-27	NC	No connection						
28-33	G[0-5]	Green data 6-bit/18bit bi-directional (D6-D11)						
34-35	NC	No connection						
36-41	R[0-5]	Red data 6-bit/18bit bi-directional (D12-D17)						
42	HSYNC	Line synchronization signal input						
43	VSYNC	Frame /Ram synchronization signal input						
44	DCLK	Dot clock signal						
45-46	AVDD	Supply voltage for lcd driving						
47-48	VCC	Supply voltage for logic						
49	DC	Parallel Interface						
50	RD	I80 system: Serves as a read signal and reads data at the low level.						
51	WR	I80 system: Serves as a write signal and writes data at the rising edge.						
		Interface selection pin						
		PS3 PS2 PS1 PS0 Interface mode						
		0 0 1 0 16-bit 8080 parallel interface, D[17:10]&D[8:1]						
		0 0 1 1 8-bit 8080 parallel interface, D[17:10]						
		$\begin{array}{c cccc} 0 & 1 & 0 & 0 & 9-\text{bit } \text{RGB}(262 \text{ colour}) + 3-\text{wire } \text{SPI}, \text{D}[17:9] \\ \hline \end{array}$						
52-55	PS[0:3]	0 1 $0$ 1 $16$ -bit RGB(262K colour) + 3-wire SPI,						
		D[17:10]&D[8:1]						
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$						
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$						
		1 0 1 0 18-bit 8080 parallel interface, D[17:0]						
		1         0         1         1         9-bit 8080 parallel interface, D[17:9]           1         1         1         0         3-wire SPI						
FC	WENNE							
56 57	WSYNC NC	Ram Write Synchronization output         No connection						
58	OE	Display enable pin from controller						
59-60	GND	Power supply (system ground)						
57-00		romer suppry (system Eround)						



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#### **5. Absolute Maximum Ratings**

#### 5.1 Electrical Maximum Ratings – for IC Only

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Table 3: Electrical Maximum Ratings – for IC

Parameter	Symbol	Min.	Max.	Unit	Note
Supply voltage	VCC	-0.3	+4.0	V	1
Input voltage	AVDD	-0.3	+5.0	V	

Note:

1.VCC, GND must be maintained.

2. The modules may be destroyed if they are used beyond the absolute maximum ratings.

#### 5.2 Environmental Condition

		Table 4				
Item	Operating temperature (Topr)		Storage temperature (Tstg) (Note 1)		Remark	
	Min.	Max.	Min.	Max.		
Ambient temperature	-20°C	+70°C	-30°C	+80°C	Dry	
Humidity (Note 1)	80 < 50% RH for 40°	temperature	No condensation			

Note 1: Product cannot sustain at extreme storage conditions for long time.

#### **6. Electrical Specifications**

#### **Typical Electrical Characteristics**

At Ta = 25 °C, VCC=IOVCC= 3.3V, GND=0V.

		Table 5				
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage (logic)	VCC-GND		1.4	-	3.6	V
Supply voltage (lcd driving)	AVDD		2.5 or VDDIO	-	3.6	V
	VGH		9	-	18.0	V
Output voltage(LCD)	VGL		-15.0	_	-6	V
	VCOM		-1	-	6	V
Supply current (Logic & LCD)	ICC	VDD=3.3V	-	-	10	mA
Supply voltage of white LED backlight	VLED	Forward current =20 mA	-	19.2	21.6	V
Luminance (on the module surface)		Number of LED dies = 6	230	270	-	cd/m <sup>2</sup>



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#### 7. Optical Characteristics

Table 7: Optical specifications								
Items		Symbol	Condition	Specifications			Unit	
nems		Symbol	Condition	Min.	Тур.	Max.	Umt	
Contrast Ra	atio	CR		150	300	-	-	
Response T	ime	$T_F + T_R$		-	35	50	ms	
	Red	X <sub>R</sub>		0.588	0.618	0.648	-	
	Keu	Y <sub>R</sub>		0.306	0.336	0.366	-	
	Green	X <sub>G</sub>		0.275	0.305	0.335	-	
Chromaticity		Y <sub>G</sub>		0.534	0.564	0.594	-	
Chromaticity	Blue	X <sub>B</sub>		0.116	0.146	0.176	-	Note
		Y <sub>B</sub>		0.077	0.107	0.137	-	
	White	$X_{W}$		-	0.307	-	-	
	w mite	$Y_{W}$		-	0.328	-	-	
	Hor.	$\phi 1(3 \text{ o'clock})$		-	45	-		
Viewing angle		\$\$\\$	Center	-	45	-	deg.	
	Ver.	$\theta 2(12 \text{ o'clock})$	CR≥10	-	15	-		
	ver.	$\theta 1(6 \text{ o'clock})$		-	35	-		
NTSC ratio					61.5		%	

Note 1: Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

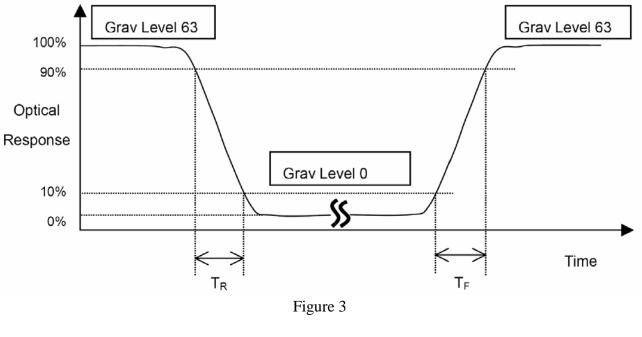
L63: Luminance of gray level 63

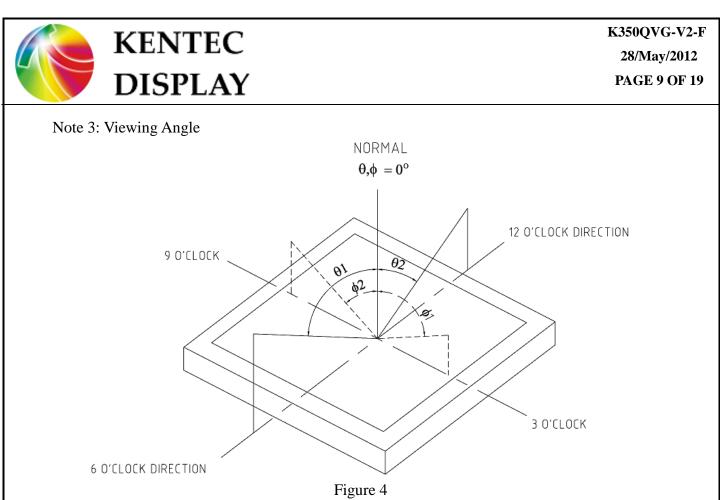
L0: Luminance of gray level 0

CR = CR (10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note 5.



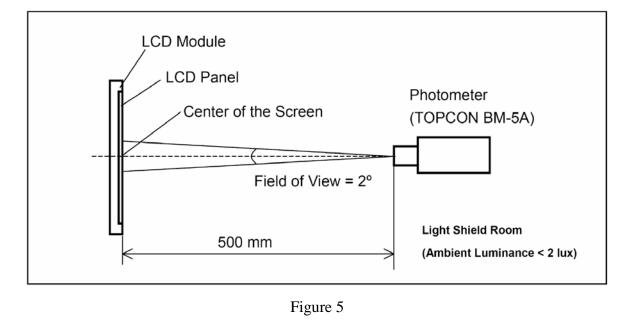




The above "Viewing Angle" is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O'clock. Module maker can increase the "Viewing Angle" by applying Wide View Film.

#### Note 4: Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.





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#### 8. AC Characteristics

Please refer SSD2119 datasheet.

#### 9. Reliability Test Item

Test Item	Sample Type	Test Condition		Test result determinant gist
High temperature	Normal temperature	70±3	<b>;9</b> 6Н	the inspection of
storage	Wide temperature	80±3	9 <b>6</b> H	appearance and function
Low temperature	Normal temperature	-20±3	<b>îQ</b> 0H	character.
storage	Wide temperature	-30±3	<b>îQ</b> 0H	
High temperature	Normal temperature	50	96HB	
/humidity storage	Wide temperature	60	96 <b>H</b> 8	
High temperature	Normal temperature	60±3	°C;96H	no objection of the function
operation	Wide temperature	70±3	°C;96H	character; no fatal objection of
Low temperature	Normal temperature	0±3	°C;96H	the appearance.
operation	Wide temperature	-20±3	°C;96H	
High temperature	Normal temperature	40	0	
/humidity operation	Wide temperature	50	0	
Temperature Shock	Normal temperature	-20±3°C,30m	in→70±3°C,30	inspect the objections
		min;1	0cycle	appearance、function & the whole structure
	Wide temperature		C,30min	The inspection of appearance,
		80±3,30m	in;10cycle	function & the whole structure

#### **10. Suggestions for using LCD modules**

#### **10.1 Handling of LCM**

- 1. The LCD screen is made of glass. Don't give excessive external shock, or drop from a high place.
- 2. If the LCD screen is damaged and the liquid crystal leaks out, do not lick and swallow. When the liquid is attach to your hand, skin, cloth etc, wash it off by using soap and water thoroughly and immediately.
- 3. Don't apply excessive force on the surface of the LCM.
- 4. If the surface is contaminated ,clean it with soft cloth. If the LCM is severely contaminated , use Isopropyl alcohol/Ethyl alcohol to clean. Other solvents may damage the polarizer . The following solvents is especially prohibited: water , ketone Aromatic solvents etc.
- 5. Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by

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water droplets, moisture condensation or a current flow in a high-humidity environment.

6. Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

7. Don't disassemble the LCM.

8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 9. Do not alter, modify or change the the shape of the tab on the metal frame.
- 10. Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- 11. Do not damage or modify the pattern writing on the printed circuit board.
- 12. Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector
- 13. Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- 14. Do not drop, bend or twist LCM.

#### 10.2 Cautions for installing and assemabling if the module has Touch Panel

1. Use a buffer material (Gasket) between the touch panel and Front-case to protect damage and wrong operating. The dimension of the buffer material's edge between the TP V.A. edge is Min. 0.3mm.

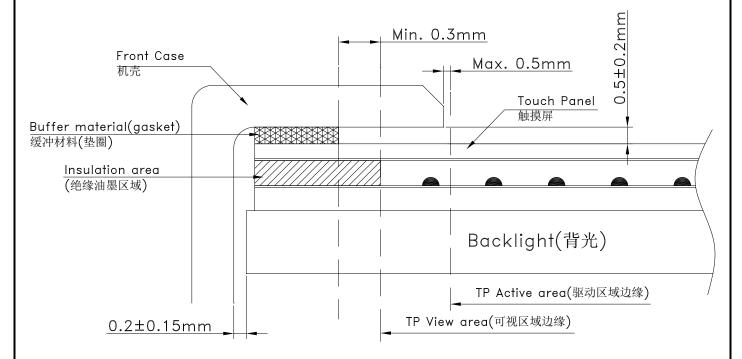
2. We recommend to design a case that it can't over the boundary of the active area Max. 0.5mm in order to prevent an operation at outside of the active area which can't guarantee the specified durability,



because operation at the outside of the active area cause serious damage of a transparent.

3. When design case for installing Module, you would consider give a distance about  $0.2\pm0.15$ mm between the module edge to case inside.

4. The corners of the product are not chamfered. When positioning and fixing the product on the case, we sugguest that you would provide a R part on the conner of the case so as not to apply load on the corner of the transparent module.



#### 10.3 Storage

1. Store in an ambient temperature of 5 to 45 °C, and in a relative humidity of 40% to 60%. Don't expose

to sunlight or fluorescent light.

- 2. Storage in a clean environment, free from dust, active gas, and solvent.
- 3. Store in antistatic container.



#### **11. Inspection Standard**

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch pannel.

#### 11.1 Sample plan and Inspection condition

11.1.1 Sample plan

Sampling plan according to MIL-STD-105E, normal level 2 and based on:

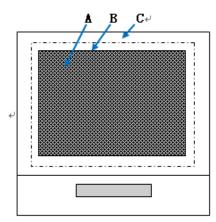
Major defect: AQL 0.65;

Minor defect: AQL 1.5.

11.1.2 Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45 against perpendicular line.

#### 11.2 Definition of inspection zone in LCD



Inspection zones in an LCD

Zone A: character/Digit area;

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area);

Zone C: Outside viewing area (invisible area after assembly in customer's product);

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product. Defects are classified as major defects and minor defects according to the degree of defectiveness defined herein.

#### 11.3 Major defects and Minor defects

11.3.1 Major defects

A major defect is a defect that is likely to result in failure, or to reduce the usability of the product for its intended purpose.

11.3.1.1 Abnormal operation: modules cannot display normally;

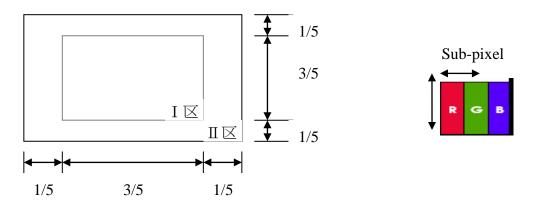


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- 11.3.1.2 Line defect;
- 11.3.1.3 There is serious distortion or sharp burr on mechanical housing;
- 11.3.1.4 Glass breakage.
- 11.3.2 Minor defects:

A minor defect is a defect that is not likely to reduce the usability of the product for its intended purpose.

- 11.3.2.1 Dot defect:
  - 11.3.2.1.1 Inspection pattern : Full white, full black, red, green and blue screens;
- 11.3.2.1.2 Criteria :(acceptable);



Note: 1. Dot defect is defined as the defective area of the dot area is larger than 50% of the dot area. And the bright dot defect must be visible through 5% ND filter.

2. Except for the allowed numbers of adjacent dots, the distance between dot defects should be more than 3mm apart.

11.3.2.1.3 The definitions of the inner display area and outer display area.

#### **11.4 Inspection standards table:**

11.4.1 Major defect

Item No.	Items to be	Items to be Inspection Standard		
11.4.1.1	All functional defects	<ol> <li>No display</li> <li>Display abnormally</li> <li>Missing vertical/horizontal segment</li> <li>Short circuit</li> <li>Back-light no lighting, flickering and abnormal lighting.</li> </ol>	Major	
11.4.1.2	Missing	Missing component		
11.4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.		
11.4.1.4	linearity	No more than 1.5%		



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#### 11.4.2 Cosmetic Defect (spot defect)

Item No	Itemsto be	Inspect	Inspection Standard						
	Clear Spot Black and white		For dark/white spot, size $\Phi$ is defined as $\Phi = (x + y)/2$						
	Spot defect		Zone Acceptable Qty						
11.4.2.1	Pinhole,	Si	ze(mm)	A B					
	Foreign	Φ≤0.1		Ignore		Minor			
	Particle,	0.10<	<Φ≤0.15	2	Ignoro	Minor			
	polarizer Dirt	0.15 <	<Φ≤0.20	1	Ignore				
	Dirt	$\Phi > 0$	.20	0					
11.4.2.2			Zone Acceptable Qty						
		Si	ze(mm)	A B	С	]			
	Clear Spot		Φ≤0.1 Ignore						
	TP Dirt	0.10<	<Φ≤0.15	2	Ignoro	Minor			
		0.15 <	<Φ≤0.25	1	Ignore				
		$\Phi > 0$	.25	0					
11.4.2.3	Dim Spots		Zone	Accept					
	Circle shaped and	Si	ze(mm)	A B	C	11			
		Ф≤0.2	2	Ignore					
	dim edged defects	0.20<	<Φ≤0.4	2	I an ana	Minor			
	uelects	0.4 <	Φ≤0.6	1	Ignore				
		$\Phi > 0$	.6	0					
11.4.2.4		dot =su	dot =sub-pixel						
			Acceptable Qty						
				Ι	II				
	Dot defect	Br	ight dot	0	2	Minor			
			ark dot	1	2				
			The distance of two point >5mm						
11.4.3 Co	smetic Defect					I			
		<u> </u>	,			Classification			
Item No	Items to be		Inspection Standard						
11.4.3.1	Line defect Black line, White line, Foreign material on polarizer	0	Size(mm) Acceptable Qty						
		5		Acce	•	-			
		L(Length)	W(Width)		zone				
			· · · ·	A	B C				
		Ignore	W≤0.02	Ignor	e	Minor			
		L≤3.0	$0.02 < W \le 0.03$	2	Ignore				
		L≤2.0	$0.03 < W \le 0.05$	1					
			W > 0.05	Define as spo	t defect				



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		ter mobile		operating cond	dition:						
					The line can be seen after mobile phone in the operating condition:						
	Size(mm)			Acceptable Qty							
I (Length)	L(Length) W(Width)		zone								
			А	В	С	Minor					
I Ignore	ore W≤0.03		Ignore		Ignore						
L≤3.0	≤3.0 0.03 <		3								
	W>0.05			spot defect							
operating con be seen only i the following	If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 11.4.3.1. If the scratch can be seen only in non-operating condition or some special angle, judge by the following.										
	Size(mm)			Acceptable Qty							
	L(Length) W(Width)		zone			Minor					
=(=====;			А	В	C	Minor					
	W≤0.02		Ignore								
L≤3.0	0.02 <	W<0.03 2									
			1 Ignore		Ignore						
			Define as	spot defect							
Air bubble											
ze			С								
Φ≤0.2	Φ≤0.2			Ignore							
$e$ 0.20 $<\Phi_{\leq}$	0.20<Φ≤0.3				Innon						
0.3<Φ≤0	0.3<Φ≤0.5		1								
	₩ > 0.5										
Defect						Classification					
	Inspection Standard										
	Chips on corner										
A:LCD Gla	A:LCD Glass defect										
$\rightarrow$											
	X Y Z										
zĴ	$\leq 0.2 \leq S$ Disregard										
Ching on the											
	ITO pad or expose perimeter seal.										
	B:TP Glass defect										
X	X Y T										
~											
	at on I Ignore I Gamma I Ignore L $\leq$ 3.0 If the scratch operating combeseen only if the following the following L(Length) Ignore L $\leq$ 3.0 L $\leq$ 2.0 Air bubble Air bubble Question Comparison Comparison Comparison Comparison Air Chips on comparison Compa	at on IIgnoreW $\leq 0.0$ IIgnoreW $\leq 0.0$ UL $\leq 3.0$ 0.03 W > 0.If the scratch can be see operating condition, jue be seen only in non-ope the following.er cratchSize(mm) U(Length)IgnoreW $\leq 0.0$ U $\leq 3.0$ L $\leq 2.0$ 0.02 < U $\leq 0.0$ L $\leq 2.0$ 0.03 < W > 0.Air bubbles betweeW > 0.Air bubbles betweeW > 0.Air bubbles betwee0.3 < $\Phi \leq 0.5$ D > 0.5DefectChips on corner A:LCD Glass defectChips on the corner of ITO pad or expose pe B:TP Glass defect	at offIgnore $W \le 0.03$ Ignore $W \le 0.03$ L \le 3.0 $0.03$ W > 0.05If the scratch can be seen after mo operating condition, judge by the I be seen only in non-operating cond the following.er 	an on a lignore $W \le 0.03$ Ig $L \le 3.0$ 0.03 Ig $L \le 3.0$ 0.03 Ig $L \le 3.0$ 0.03 Ig $L \le 3.0$ 0.03 Ig $L \le 3.0$ 0.05 Define as If the scratch can be seen after mobile phone or operating condition, judge by the line defect of be seen only in non-operating condition or som the following. I (Length) W(Width) A Ignore $W \le 0.02$ Ig $L \le 3.0$ 0.02 < $W \le 0.03$ $L \le 2.0$ 0.03 < $W \le 0.05$ W > 0.05 Define as Air bubbles between glass & polarizer A A A = 0 A = 0 A = 0 A = 0 $A = 0.20 < \Phi \le 0.3$ $2 = 0.3 < \Phi \le 0.5$ 0 Defect to be Inspection Standard Chips on corner A:LCD Glass defect A = 0 A = 0	an off       Ignore       W $\leq 0.03$ Ignore         Ignore       I $\leq 3.0$ 0.03       3         W $\geq 0.05$ Define as spot defect         If the scratch can be seen after mobile phone cover assemblin operating condition, judge by the line defect of 11.4.3.1. If the seen only in non-operating condition or some special angle the following.         er       Size(mm)       Acceptable Q         L(Length)       W(Width)       A       B         Ignore       W $\leq 0.02$ Ignore       I         L(Length)       W(Width)       A       B         Ignore       W $\leq 0.02$ Ignore       I         L $\leq 2.0$ 0.03 < W $\leq 0.05$ 1       Define as spot defect         Air bubbles between glass & polarizer       Acceptable Qty       A       B         Question       Question       Question       Question       Question         ze       e       O.20 < $\Phi \leq 0.3$ 2       Question       Question         e       O.3 < $\Phi \leq 0.5$ 1       Question       Question       Question       Question         Defect       Inspection Standard       Chips on corner       A: LCD Glass defect       X       Y $\leq 0.2$ $\leq 0.2$ $\leq 0.2$ $\leq 0.2$	a on lignore $W \le 0.03$ Ignore Ignore Is $A + B$ C Ignore $W \le 0.03$ Ignore Ignore Is $W > 0.03$ O Define as spot defect If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 11.4.3.1. If the scratch can be seen only in non-operating condition or some special angle, judge by the following. Size(mm) Acceptable Qty L(Length) W(Width) A B C Ignore $W \le 0.02$ Ignore Is $2.00$ O $0.03 < W \le 0.05$ Define as spot defect L $\le 3.0$ O $0.02 < W \le 0.03$ 2 I $\le 2.0$ O $0.03 < W \le 0.05$ 1 Ignore M $\ge 0.05$ Define as spot defect Air bubbles between glass & polarizer Perevent A B C 4 xir bubbles between glass & polarizer Air bubbles between glass $x = 0$ Ignore O $0.20 < \Phi \le 0.3$ 2 $0.3 < \Phi \le 0.5$ 1 $\Phi > 0.5$ 0 Defect To be Inspection Standard Chips on corner A:LCD Glass defect $X = \frac{X + Z}{2}$ S=contact pad length Chips on the corner of terminal shall not be allowed to extend into the TIO pad or expose perimeter seal. B:TP Glass defect $X = \frac{X + Z}{2}$ $X + Z$					

